

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0073] at page 36 of the original specification with the following amended paragraph:

Bumps 3 were then formed on the electrode pads 5. The bumps 3 were formed from lead-free solder containing copper as well as 3 mass% Sn and 0.5 mass% Ag. In this case, the sum of the heights of the electrode pads 5 and bumps 3, i.e., the height C shown in FIG. 4A, was 50 μm . Bumps were not formed on the electrodes 4 of three semiconductor elements 2 of the ~~six~~ five semiconductor elements 2. The same bumps as those formed on the electrode pads 5 of the electrodes 4 were formed on the remaining two semiconductor elements 2.